## PATENT SPECIFICATION

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## (54) RAPIDLY-HARDENABLE RESIN AND USE THEREOF

(71) We, SIKA AG VORMALS KASPAR WINKLER & CO., a Swiss Company of Tüffenwies 16.22, Zürich, Switzerland, do hereby declare the invention, for which we pray that a patent may be granted to us, and the method by which it is to be performed, to be particularly described in and by the following statement:-

The present invention concerns improvements in rapid-hardening resins of

the type comprising an epoxide resin and an amine hardener.

Cold hardenable mixtures of epoxide resins and amines, preferably polyamides containing amino groups have been used for a considerable time in the construction industry as coating substances, coverings, mortar, adhesive, injection agent and for impregnation purposes.

The hardening time of such mixtures, in other words the time required for the mixtures to reach a condition where they can be used is dependent upon temperature. Generally, the hardening reaction at temperatures beneath about 8°C proceeds so slowly that such mixtures can no longer be employed.

It has already been proposed to add to such hardenable mixtures, compounds

which accelerate the hardening reaction.

A disadvantage of this proposal is that the accelerator, which is not consumed during the hardening reaction, unfavourably affects the properties of the hardened mixture, for example, the surface hardness, the resistance against the effects of water and chemicals and the mechanical strength, and thus such accelerators can only be added in limited quantities. Hence, the possibility of using the hardenable mixture containing the accelerator is limited to temperatures above about 5°C and furthermore, since most of the accelerators are toxic soluble compounds, it should be apparent that epoxide resins containing accelerators generally cannot be used in the construction of swimming pools or drinking water installations. It is therefore an object of the present invention to provide a rapidly hardening synthetic resin which substantially overcomes the aforementioned drawbacks and

According to the present invention we provide a curable epoxy resinous 30 composition comprising an epoxide resin, an amine hardener and as an accelerator an episulphide compound or compounds, the episulphide compound or compounds having on the average more than one



group per molecule and an apisulphide value in the range of 0.2 to 0.9 and the ratio of the epoxide resin to the episulphide compound or compounds being selected so that the resin composition hardens in the temperature range of -30°C to +10°C. As used hereinafter the term "episulphide value" indicates the number of equivalents of episulphide sulphur per 100 gms.

Preferably the episulphide compound or compounds has an episulphide value in the range of 0.5 to 0.9 The episulphide compounds markedly accelerate the hardening of epoxide resins by means of amine hardeners at low temperatures as a function of their dosage.

Preferably the episulphide compound or compounds comprises from 10 to 30% by weight of the total weight of the episulphide compound or compounds.

The following Table 1 shows the accelerating influence of an episulfide compound upon the hardening of an epoxide resin of the bisphenol A-type by means of an amine hardener. The mixing ratio of resin:hardener is 4:1 parts by weight, the amine hardener contains 10% by weight triethylenetetramine (TETA) and the resin component contains the quantities of episulfide compounds, having an episulfide value of 0.78, shown in Table 1 below.

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	Inventive Mixture				Without Episulfide Compounds			
Resin component (parts by weight)	80	80	80	80	80	80	80	80
Amine Hardener (parts by weight)	20	20	20	20	20	20	20	20
Episulfide compound (parts by weight)	20	20	20	20	-	_	_	~
Temperature (°C)	+10	+5	0	-5	+10	+5	0	-5
Processing Time (minutes)	. 8	12	15	30	120	600	00	00

Example 2.

The following Table 2 illustrates the influence of the dosing of episulfide compound in Table 1 upon the hardening speed of the resin-hardener-mixture employed in Table 1. The amine hardener contains 10% by weight TETA.

TABLE 2

Episulfide compound (parts by weight)	30	20	15	10
Temperature (°C)	0	0	0	0
Processing Time (minutes)	8	15	18	30

Example 3.

The following Table 3 illustrates the influence of the dosing of the dimthylenetriamine (DETA) upon the hardening speed of the resin-amine hardener mixture used in Table 1, wherein the resin component contains 10% by weight of an episulfide compound having an "episulfide value" of 0.60 and the hardener component contains the quantities of DETA (% by weight) given in Table 3.

TABLE 3

DETA	5	8	10	12
Temperature (°C)	5	5	5	5
Processing Time (minutes)	28	20	15	12

Example 4.

Example 4.

The following Table 4 illustrates the development of the Brinell hardness at a temperature of 10°C and -5°C for a non-accelerated and an accelerated resinhardener-mixture. The non-accelerated mixture comprised a 100 g mixture of an aliphatic epoxy resin (formed by reacting glycerol and epichlorohydrin) and an amine hardener in a ratio of 3:1. The accelerated mixture comprised a similar 100 gm. mixture but in which the epoxide resin contained 25% by weight of the episulfide compound of Table 1 and the accelerated resin component contained 15°% by weight TETA.

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Temperature (°C)		10		-5			
Brinell Hardness (kp/cm²) after hour	10	50	100	10'	50	100	
Accelerated	360	1180	1250	230	780	1050	
Non-Accelerated	20	93	220	±0	±0	±0	

## WHAT WE CLAIM IS:-

1. A curable epoxy resinous composition comprising an epoxide resin, an amine hardener and as an accelerator an episulphide compound or compounds, the episulphide compound or compounds having on the average more than one

(-CH-CH<sub>2</sub>)

group per molecule and an episulphide value in the range of 0.2 to 0.9 and the ratio of the epoxide resin to the episulphide compound or compounds being selected so that the resin composition hardens in the temperature range of -30°C. to +10°C.

2. A composition according to claim 1 wherein the episulphide compound or compounds has an episulphide value in the range of 0.5 to 0.9 episulphide equivalents per 100 gms.

3. A composition according to claim 1 or claim 2 wherein the episulphide compound or compounds comprises from 10 to 30% by weight of the total weight of the epoxide resin and the episulphide compounds.

4. A composition according to any one of the preceding claims wherein the amine hardener comprises an aliphatic or cycloaliphatic polyamine.

5. A composition according to any one of the preceding claims wherein the amine hardener includes any one of diethylenetriamine (DETA), triethylenetriamine (DETA). tetramine (TETA), tetraethylenepentamine (TEPA), or mixtures of DETA, TETA

or TEPA. 6. A composition according to any one of the preceding claims wherein the

epoxide resin is a diglycidyl ether of bisphenol A. 7. A composition according to any one of the preceding claims including any

one of the following additives: surface active agents, levelling agents, wetting agents, delustering or dulling agents, fillers, pigments, plasticizers, extenders.

8. A curable epoxy resinous composition substantially as hereinbefore described with reference to the accompanying examples 2 and 3 and to the accelerated compositions of examples 1 and 4.

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